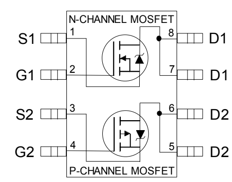
infineon

AUTOMOTIVE GRADE

AUIRF7319Q

Features

- Advanced Planar Technology
- Low On-Resistance
- Logic Level Gate Drive
- Dual N and P Channel MOSFET
- Surface Mount
- Fully Avalanche Rated
- Lead-Free, RoHS Compliant
- Automotive Qualified *



Top View

	N-CH	P-CH
V_{DSS}	30V	-30V
$R_{DS(on)}$ typ.	0.023Ω	0.042Ω
max.	0.029Ω	0.058Ω
I_D	6.5A	-4.9A

SO-8
AUIRF7319Q

Description

Specifically designed for Automotive applications, these HEXFET® Power MOSFET's in a Dual SO-8 package utilize the lastest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of these Automotive qualified HEXFET Power MOSFET's are a 150°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These benefits combine to make this design an extremely efficient and reliable device for use in Automotive applications and a wide variety of other applications.
The efficient SO-8 package provides enhanced thermal characteristics and dual MOSFET die capability making it ideal in a variety of power applications. This dual, surface mount SO-8 can dramatically reduce board space and is also available in Tape & Reel.

G	D	S
Gate	Drain	Source

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRF7319Q	SO-8	Tape and Reel	4000	AUIRF7319QTR

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

Symbol	Parameter	Max.		Units
		N-Channel	P-Channel	
V_{DS}	Drain-Source Voltage	30	-30	V
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ 10V	6.5	-4.9	A
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ 10V	5.2	-3.9	
I_{DM}	Pulsed Drain Current ①	30	-30	
I_S	Continuous Source Current (Diode Conduction)	2.5	-2.5	
P_D @T_A = 25°C	Maximum Power Dissipation ⑤	2.0		W
P_D @T_A = 70°C	Maximum Power Dissipation ⑤	1.3		
E_{AS}	Single Pulse Avalanche Energy (Thermally Limited) ③	82	140	mJ
I_{AR}	Avalanche Current	4.0	-2.8	A
E_{AR}	Repetitive Avalanche Energy	0.20		mJ
V_{GS}	Gate-to-Source Voltage	± 20		V
dv/dt	Peak Diode Recovery dv/dt ②	5.0	-5.0	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 150		°C

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount, steady state) ⑤	——	62.5	°C/W

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*Qualification standards can be found at www.infineon.com

Static @ T_J = 25°C (unless otherwise specified)

	Parameter		Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	N-Ch	30	—	—	V	V_{GS} = 0V, I_D = 250µA
		P-Ch	-30	—	—		V_{GS} = 0V, I_D = -250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	N-Ch	—	0.022	—	V/°C	Reference to 25°C, I_D = 1mA
		P-Ch	—	-0.022	—		Reference to 25°C, I_D = -1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	N-Ch	—	0.023	0.029	Ω	V_{GS} = 10V, I_D = 5.8A ④
			—	0.032	0.046		V_{GS} = 4.5V, I_D = 4.7A ④
		P-Ch	—	0.042	0.058		V_{GS} = -10V, I_D = -4.9A ⑤
			—	0.076	0.098		V_{GS} = -4.5V, I_D = -3.6A ④
$V_{GS(th)}$	Gate Threshold Voltage	N-Ch	1.0	—	3.0	V	V_{DS} = V_{GS}, I_D = 250µA
		P-Ch	-1.0	—	-3.0		V_{DS} = V_{GS}, I_D = -250µA
gfs	Forward Trans conductance	N-Ch	—	14	—	S	V_{DS} = 15V, I_D = 5.8A④
		P-Ch	—	7.7	—		V_{DS} = -15V, I_D = -4.9A④
I_{DSS}	Drain-to-Source Leakage Current	N-Ch	—	—	1.0	µA	V_{DS} =24V, V_{GS} = 0V
		P-Ch	—	—	-1.0		V_{DS} = -24V,V_{GS} = 0V
		N-Ch	—	—	25		V_{DS} =24V, V_{GS} = 0V ,T_J = 55°C
		P-Ch	—	—	-25		V_{DS} = -24V,V_{GS} = 0V,T_J = 55°C
I_{GSS}	Gate-to-Source Forward Leakage	N-P	—	—	± 100	nA	V_{GS} = ± 20V
	Gate-to-Source Reverse Leakage	N-P	—	—	± 100		V_{GS} = ± 20V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter		Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge	N-Ch	—	22	33	nC	N-Channel I_D = 5.8A, V_{DS} = 15V,V_{GS} = 10V ④ P-Channel I_D = -4.9A,V_{DS} = -15V,V_{GS} = -10V
		P-Ch	—	23	34		
Q_{gs}	Gate-to-Source Charge	N-Ch	—	2.6	3.9		
		P-Ch	—	3.8	5.7		
Q_{gd}	Gate-to-Drain Charge	N-Ch	—	6.4	9.6		
		P-Ch	—	5.9	8.9		
$t_{d(on)}$	Turn-On Delay Time	N-Ch	—	8.1	12	ns	N-Channel V_{DD} = 15V,I_D = 1.0A,R_G = 6.0Ω, R_D = 15Ω ④ P-Channel V_{DD} = -15V,I_D = -1.0A,R_G = 6.0Ω, R_D = 15Ω
		P-Ch	—	13	19		
t_r	Rise Time	N-Ch	—	8.9	13		
		P-Ch	—	13	20		
$t_{d(off)}$	Turn-Off Delay Time	N-Ch	—	26	39		
		P-Ch	—	34	51		
t_f	Fall Time	N-Ch	—	17	26		
		P-Ch	—	32	48		
C_{iss}	Input Capacitance	N-Ch	—	650	—	pF	N-Channel V_{GS} = 0V,V_{DS} = 25V,f = 1.0MHz P-Channel V_{GS} = 0V,V_{DS} = -25V,f = 1.0MHz
		P-Ch	—	710	—		
C_{oss}	Output Capacitance	N-Ch	—	320	—		
		P-Ch	—	380	—		
C_{rss}	Reverse Transfer Capacitance	N-Ch	—	130	—		
		P-Ch		180	—		

Diode Characteristics

	Parameter		Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	N-Ch	—	—	2.5	A	
		P-Ch	—	—	-2.5		
I_{SM}	Pulsed Source Current (Body Diode) ①	N-Ch	—	—	30		
		P-Ch	—	—	-30		
V_{SD}	Diode Forward Voltage	N-Ch	—	0.78	1.0	V	T_J = 25°C,I_S = 1.7A,V_{GS} = 0V ④
		P-Ch	—	-0.78	-1.0		T_J = 25°C,I_S = -1.7A,V_{GS} = 0V ④
t_{rr}	Reverse Recovery Time	N-Ch	—	45	68	ns	N-Channel T_J = 25°C ,I_F = 1.7A, di/dt = 100A/µs P-Channel ④ T_J = 25°C,I_F = -1.7A, di/dt = 100A/µs
		P-Ch	—	44	66		
Q_{rr}	Reverse Recovery Charge	N-Ch	—	58	87	nC	
		P-Ch		42	63		

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See Fig. 22)

② N-Channel $I_{SD} \leq 4.0A$, di/dt ≤ 74A/µs, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150°C$.
P-Channel $I_{SD} \leq -2.8A$, di/dt ≤ 150A/µs, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150°C$

③ N-Channel Starting T_J = 25°C, L = 10mH, R_G = 25Ω, I_{AS} = 4.0A. (See Fig. 12)
P-Channel Starting T_J = 25°C, L = 35mH, R_G = 25Ω, I_{AS} = -2.8A.

④ Pulse width ≤ 300µs; duty cycle ≤ 2%.

⑤ Surface mounted on FR-4 board , t ≤ 10sec.

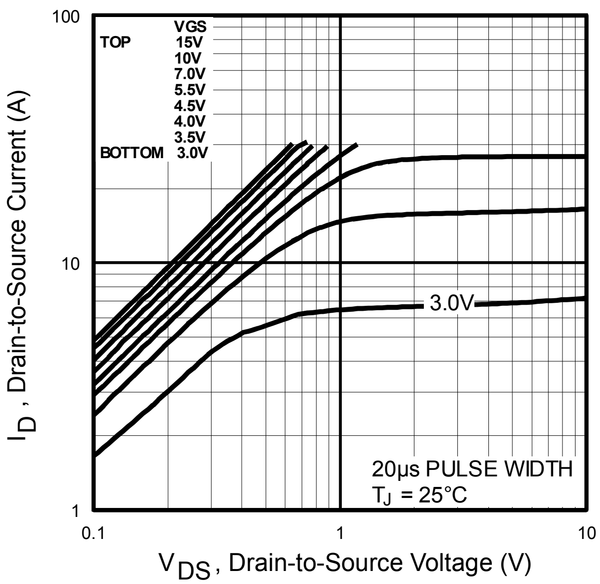


Fig. 1 Typical Output Characteristics

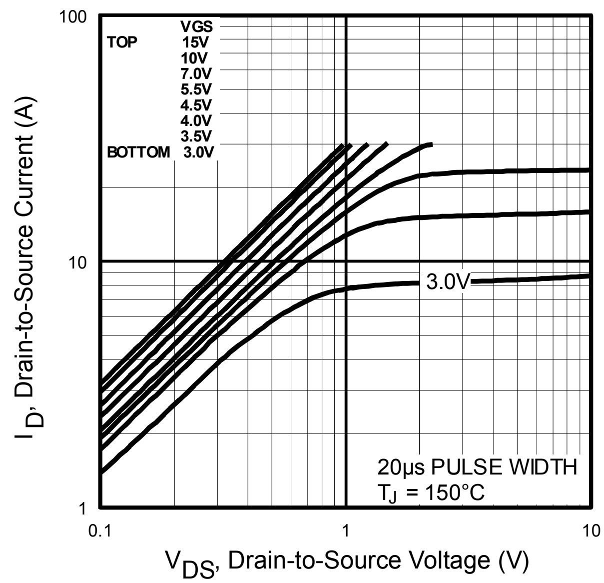


Fig. 2 Typical Output Characteristics

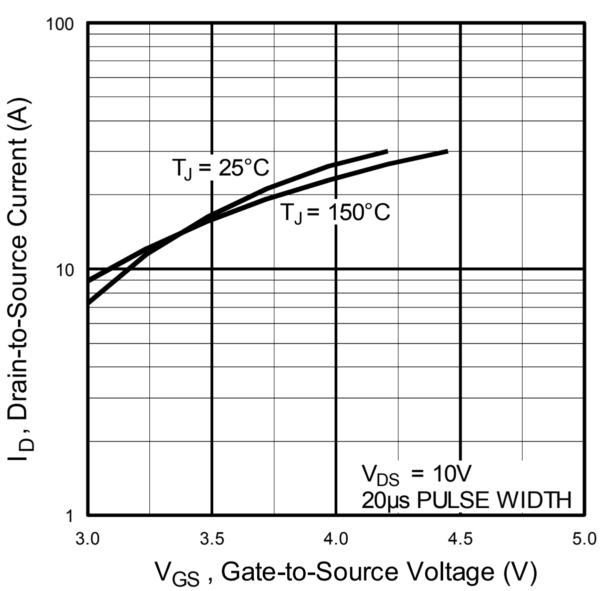


Fig. 3 Typical Transfer Characteristics

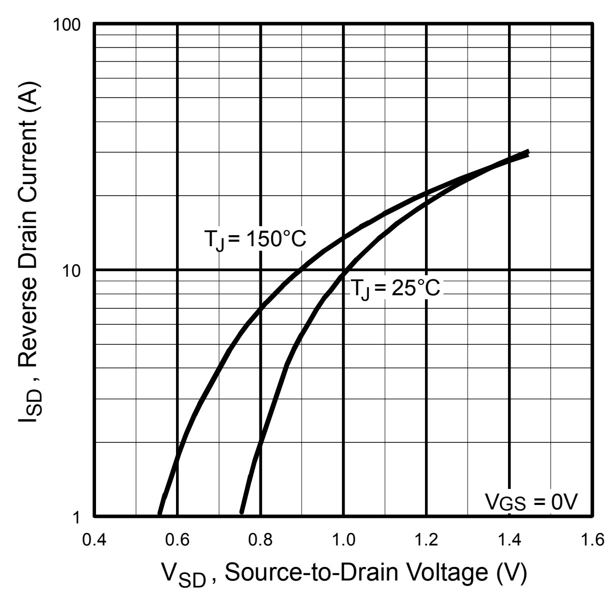


Fig. 4 Typical Source-Drain Diode Forward Voltage

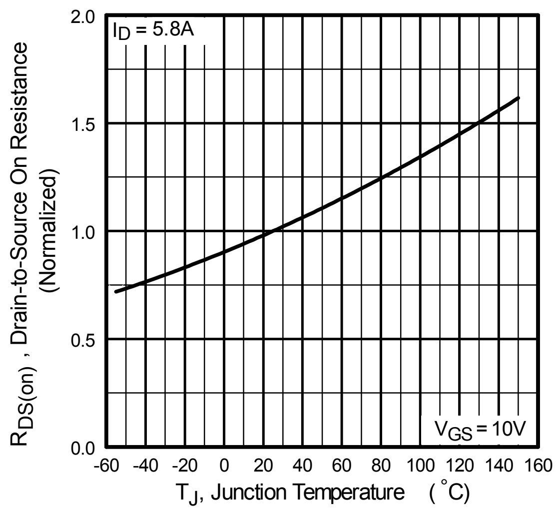


Fig 5. Normalized On-Resistance Vs. Temperature

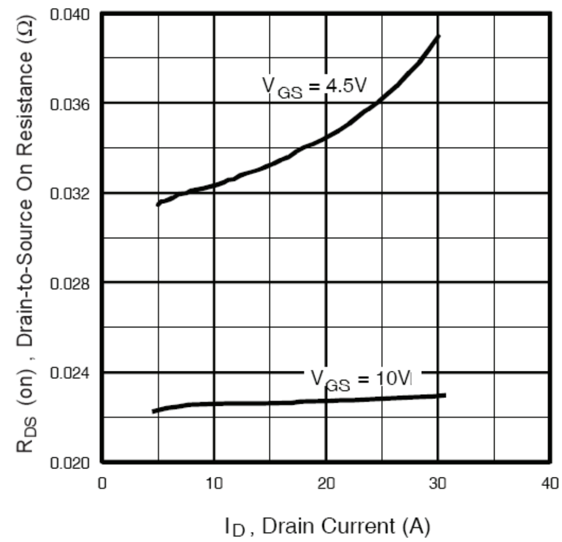


Fig 6. Typical On-Resistance Vs. Drain Current

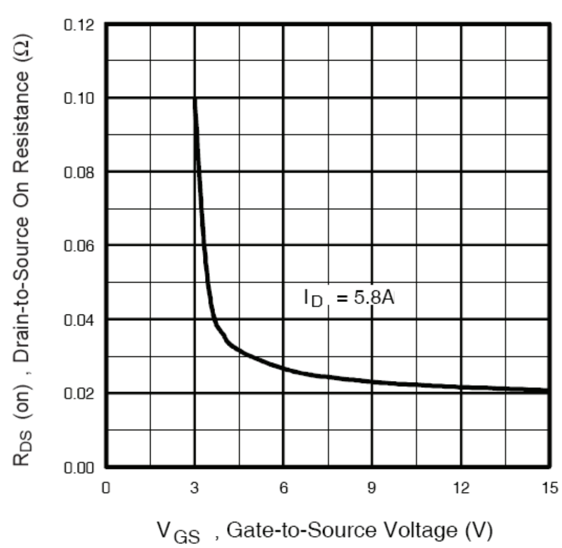


Fig. 7 Typical On-Resistance Vs. Gate Voltage

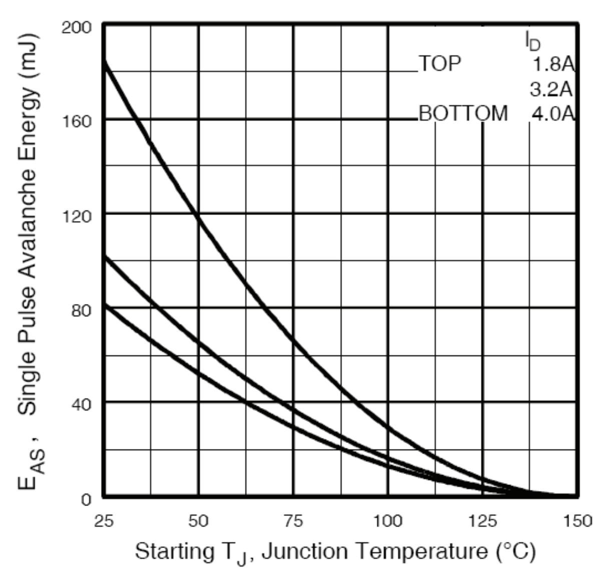


Fig 8. Maximum Avalanche Energy Vs. Drain Current

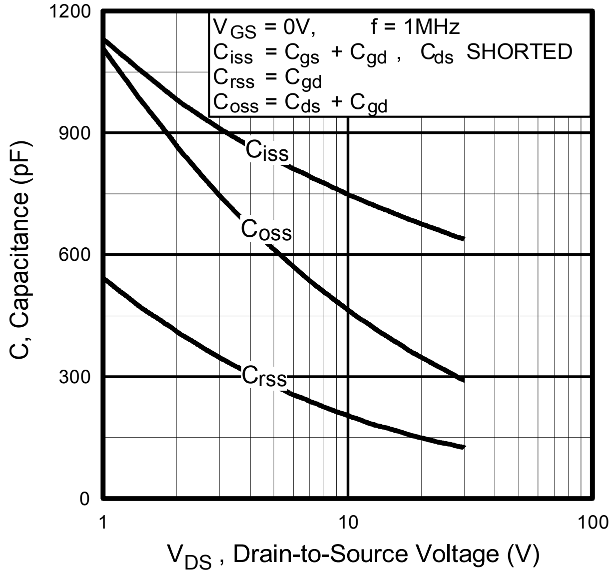


Fig 9. Typical Capacitance Vs. Drain-to-Source Voltage

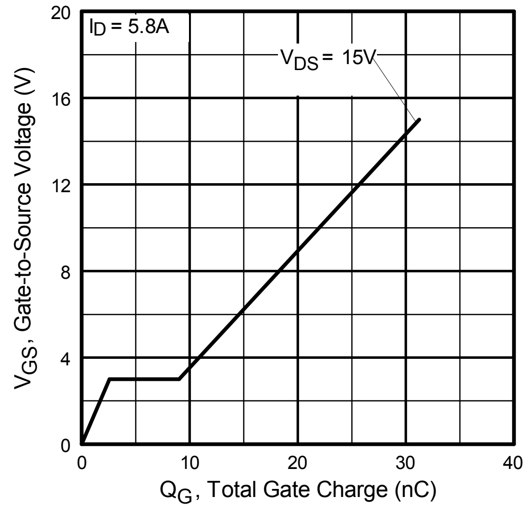


Fig 10. Typical Gate Charge Vs. Gate-to-Source Voltage

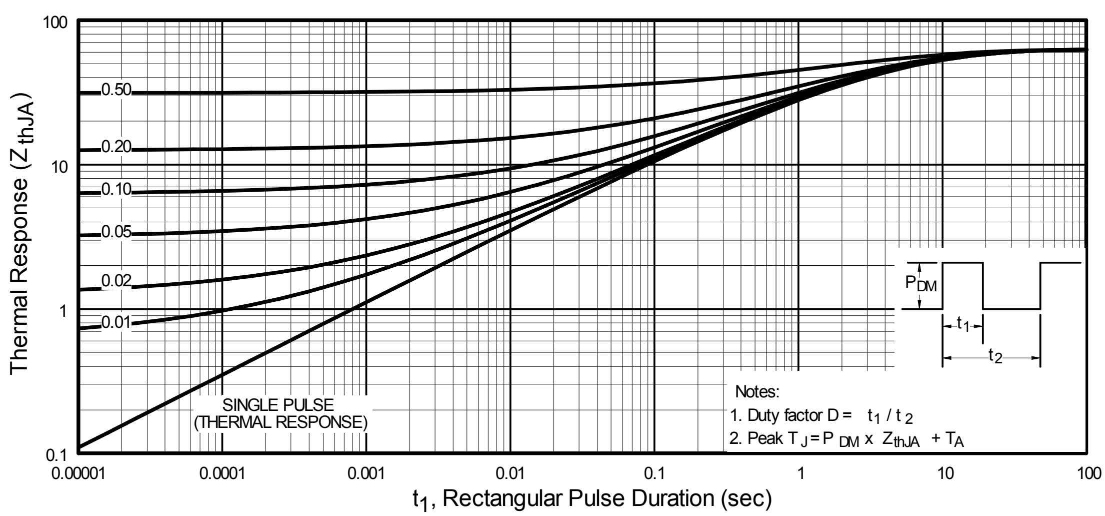


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

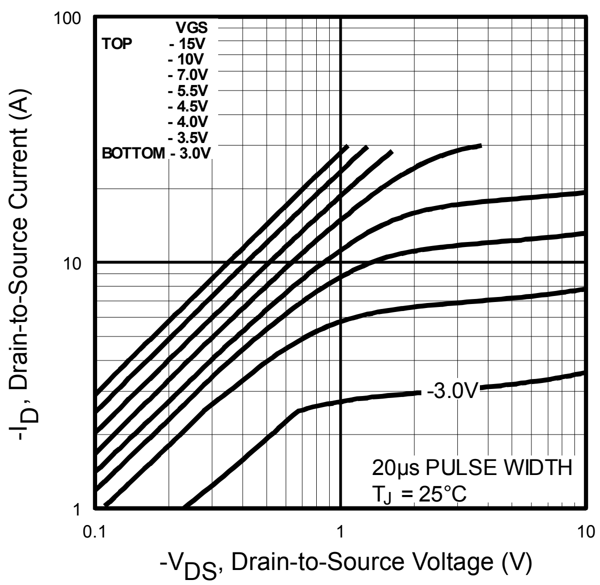


Fig. 12 Typical Output Characteristics

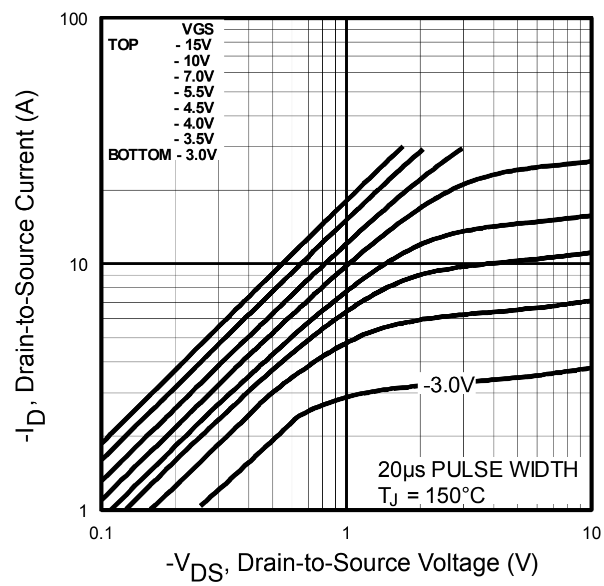


Fig. 13 Typical Output Characteristics

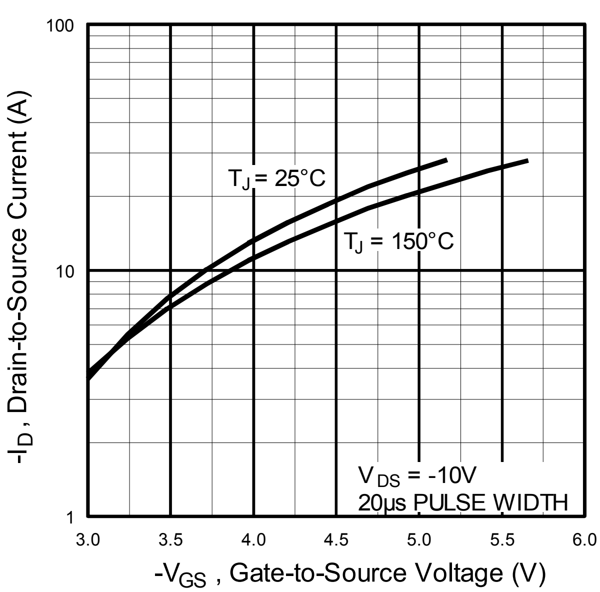


Fig. 14 Typical Transfer Characteristics

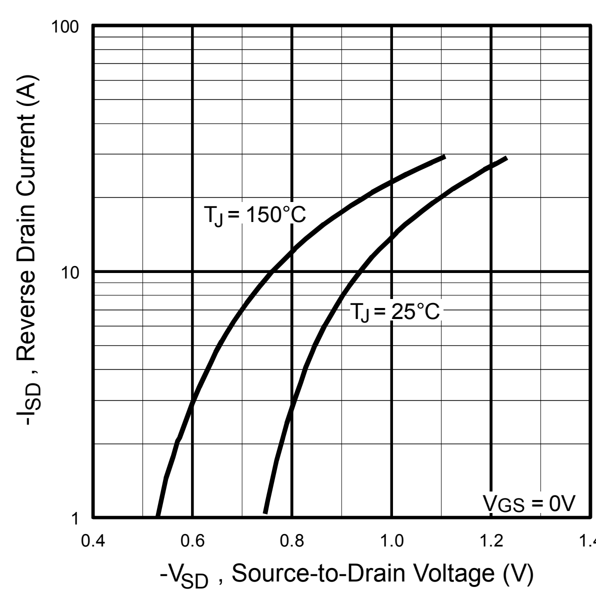


Fig. 15 Typical Source-Drain Diode Forward Voltage

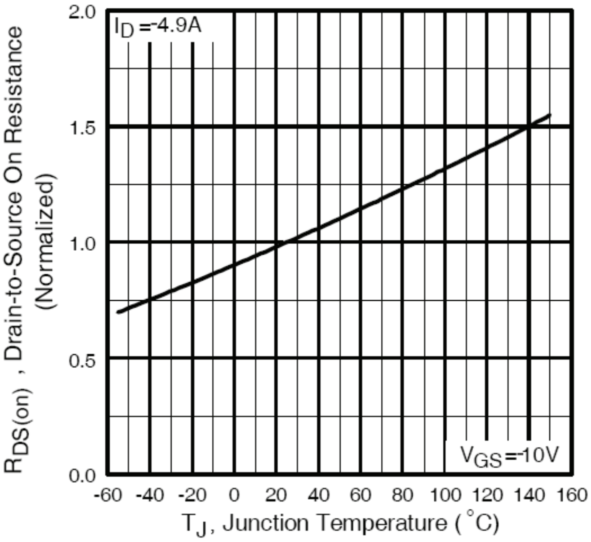


Fig 16. Normalized On-Resistance Vs. Temperature

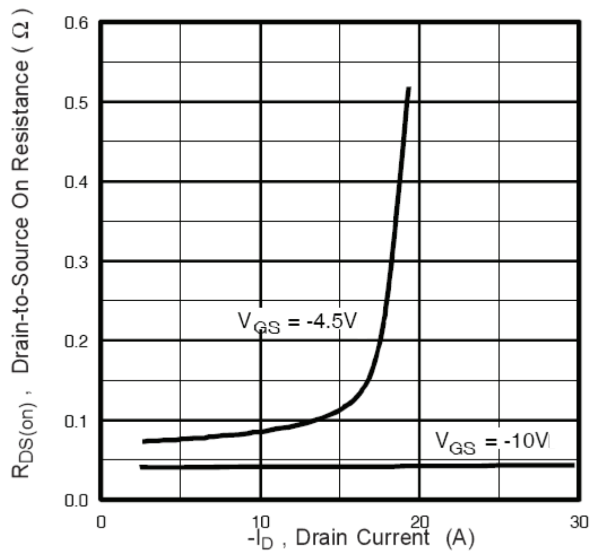


Fig 17. Typical On-Resistance Vs. Drain Current

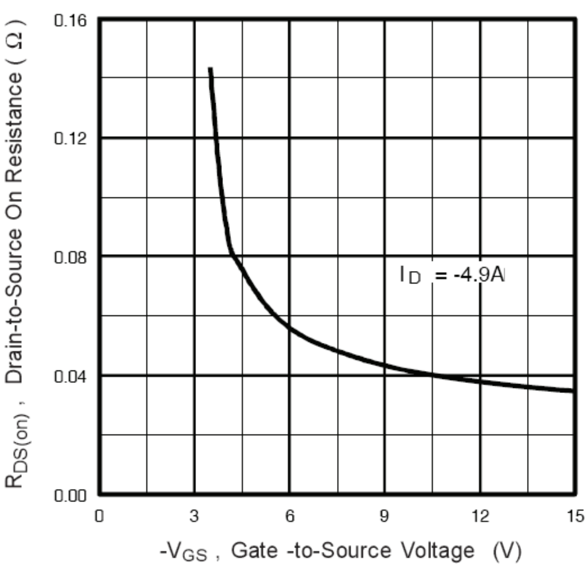


Fig. 18 Typical On-Resistance Vs. Gate Voltage

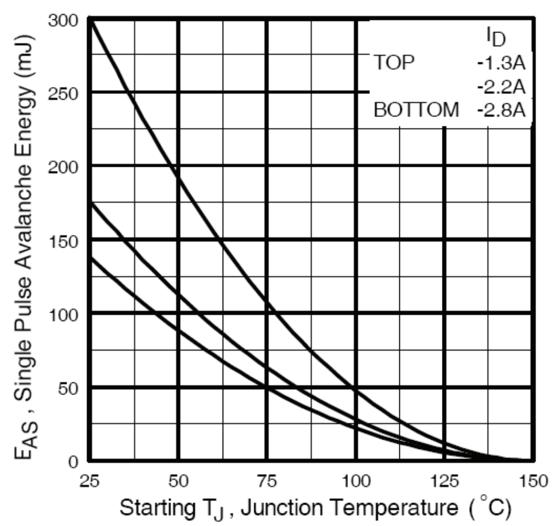


Fig 19. Maximum Avalanche Energy Vs. Drain Current

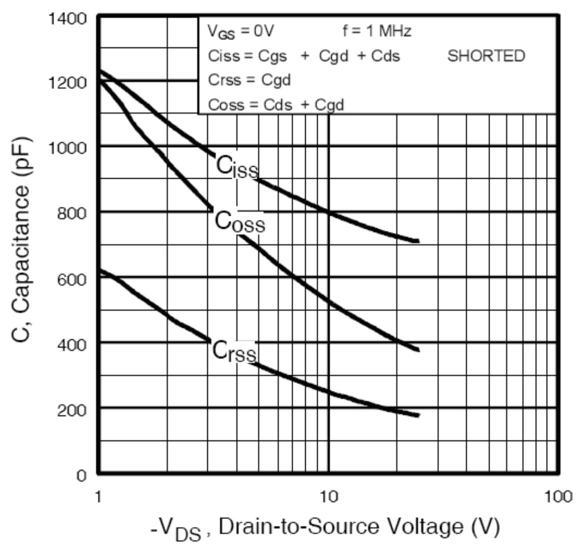


Fig 20. Typical Capacitance Vs. Drain-to-Source Voltage

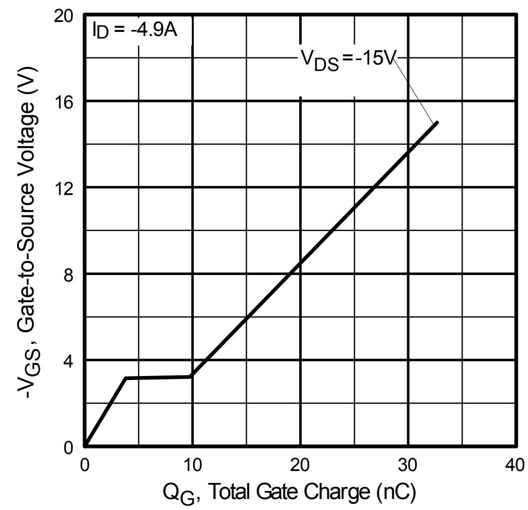


Fig 21. Typical Gate Charge Vs. Gate-to-Source Voltage

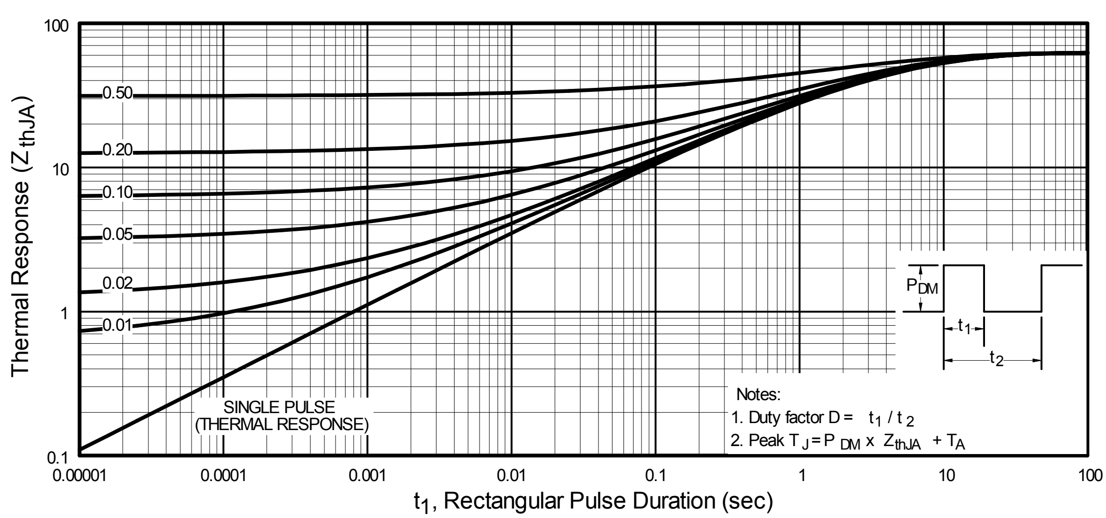
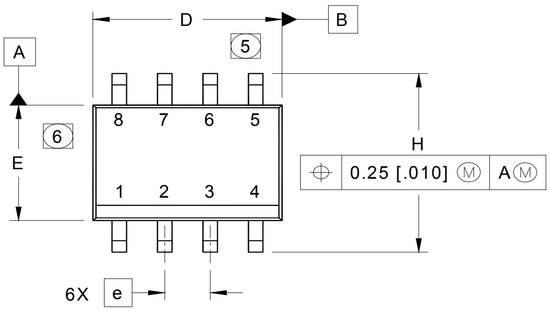
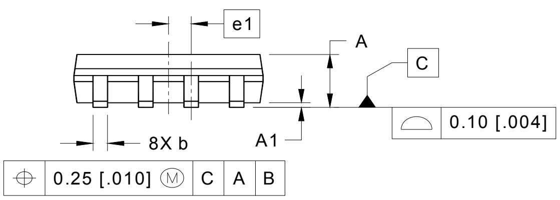


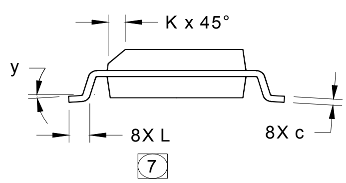
Fig 22. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

SO-8 Package Outline (Dimensions are shown in millimeters (inches))



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e 1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°

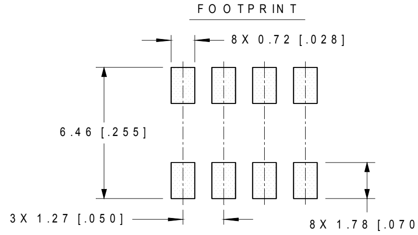




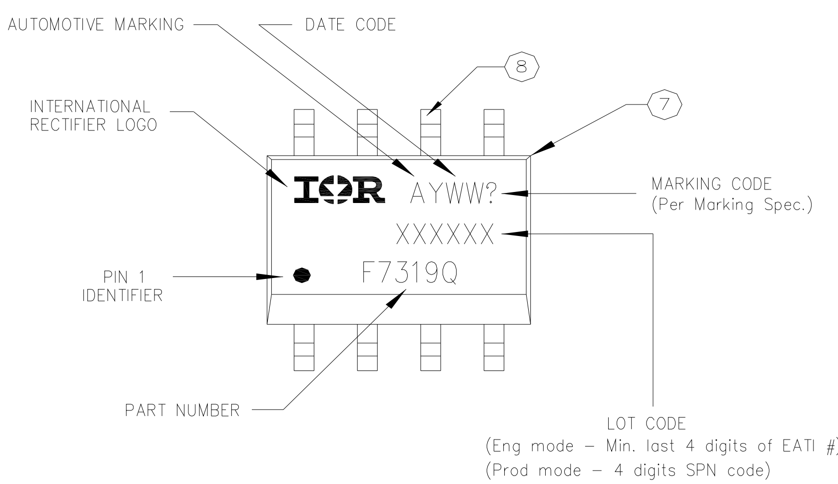
NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [.006].
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [.010].
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

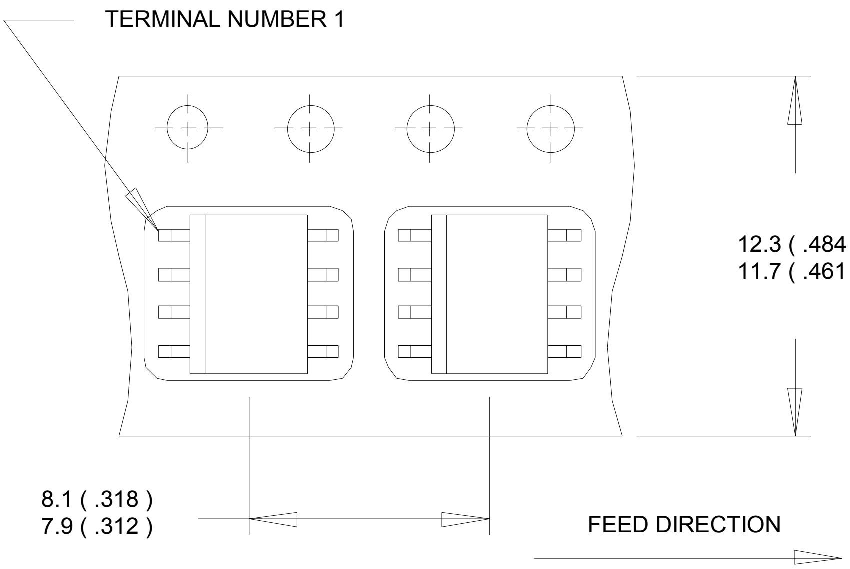
FOOTPRINT



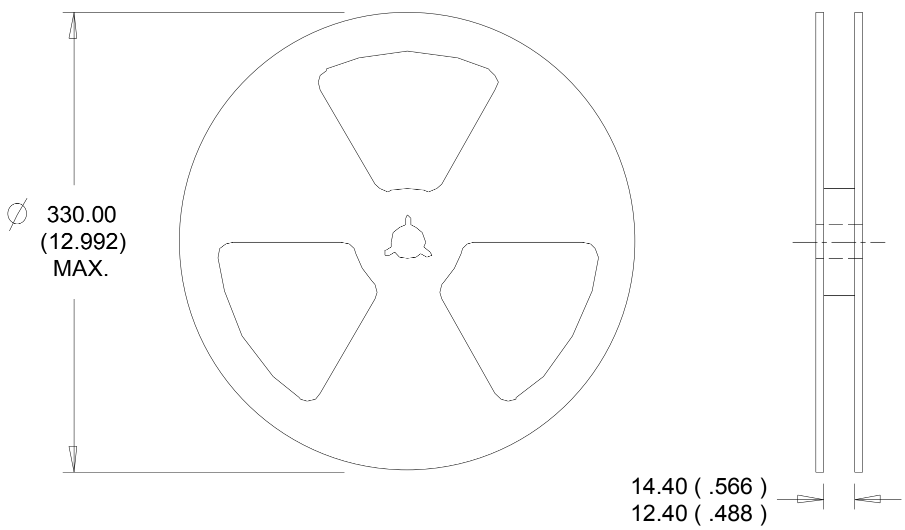
SO-8 Part Marking Information



SO-8 Tape and Reel (Dimensions are shown in millimeters (inches)



NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Qualification Information

Qualification Level		Automotive (per AEC-Q101)	
		Comments: This part number(s) passed Automotive qualification. Infineon's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		SO-8	MSL1
ESD	Machine Model	Class M2 (+/- 200V)† AEC-Q101-002	
	Human Body Model	Class H1A (+/- 500V)† AEC-Q101-001	
	Charged Device Model	Class C5 (+/- 2000V)† AEC-Q101-005	
RoHS Compliant		Yes	

† Highest passing voltage.

Revision History

Date	Comments
3/4/2014	• Added "Logic Level Gate Drive" bullet in the features section on page 1 • Updated data sheet with new IR corporate template
9/30/2015	• Updated datasheet with corporate template • Corrected ordering table on page 1.

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LifeElectronics
Живое партнерство

ООО «ЛайфЭлектроникс» "LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- *Конкурентоспособные цены и скидки постоянным клиентам.*
- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

- *Сертификаты соответствия на поставляемую продукцию (по желанию клиента).*
- *Тестирование поставляемой продукции.*
- *Поставку компонентов, требующих военную и космическую приемку.*
- *Входной контроль качества.*
- *Наличие сертификата ISO.*

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- *Регистрацию проекта у производителя компонентов.*
- *Техническую поддержку проекта.*
- *Защиту от снятия компонента с производства.*
- *Оценку стоимости проекта по компонентам.*
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